

# XENOY™ RESIN X2420

REGION ASIA

## DESCRIPTION

XENOYX2420 is a 10% glass filled, high flow, impact modified, injection moldable grade designed for high flow and impact strength. X2420 has enhanced melt flowability, impact ductility and broad color space.

## TYPICAL PROPERTY VALUES

Revision 20181012

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
<b>MECHANICAL</b>			
Tensile Stress, yld, Type I, 5 mm/min	50	MPa	ASTM D 638
Tensile Stress, brk, Type I, 5 mm/min	35	MPa	ASTM D 638
Tensile Strain, yld, Type I, 5 mm/min	3	%	ASTM D 638
Tensile Modulus, 5 mm/min	3800	MPa	ASTM D 638
Flexural Stress, yld, 1.3 mm/min, 50 mm span	90	MPa	ASTM D 790
Flexural Modulus, 1.3 mm/min, 50 mm span	3500	MPa	ASTM D 790
Tensile Stress, yield, 5 mm/min	51	MPa	ISO 527
Tensile Stress, break, 5 mm/min	37	MPa	ISO 527
Tensile Strain, yield, 5 mm/min	3	%	ISO 527
Tensile Strain, break, 5 mm/min	7	%	ISO 527
<b>IMPACT</b>			
Izod Impact, unnotched, 23°C	1600	J/m	ASTM D 4812
Izod Impact, notched, 23°C	205	J/m	ASTM D 256
Instrumented Impact Total Energy, 23°C	36	J	ASTM D 3763
Izod Impact, unnotched 80°10°4 +23°C	110	kJ/m <sup>2</sup>	ISO 180/1U
Izod Impact, unnotched 80°10°4 -30°C	74	kJ/m <sup>2</sup>	ISO 180/1U
Izod Impact, notched 80°10°4 +23°C	14	kJ/m <sup>2</sup>	ISO 180/1A
Izod Impact, notched 80°10°4 -30°C	8	kJ/m <sup>2</sup>	ISO 180/1A
Charpy 23°C, V-notch Edgew 80°10°4 sp=62mm	15	kJ/m <sup>2</sup>	ISO 179/1eA
Charpy -30°C, V-notch Edgew 80°10°4 sp=62mm	7	kJ/m <sup>2</sup>	ISO 179/1eA
Charpy 23°C, Unnotch Edgew 80°10°4 sp=62mm	95	kJ/m <sup>2</sup>	ISO 179/1eU
Charpy -30°C, Unnotch Edgew 80°10°4 sp=62mm	95	kJ/m <sup>2</sup>	ISO 179/1eU
<b>THERMAL</b>			
HDT, 0.45 MPa, 3.2 mm, unannealed	111	°C	ASTM D 648
HDT, 1.82 MPa, 3.2mm, unannealed	101	°C	ASTM D 648
CTE, -40°C to 40°C, flow	5.E-05	1/°C	ASTM E 831
CTE, -40°C to 40°C, xflow	8.E-05	1/°C	ASTM E 831
CTE, 23°C to 80°C, flow	4.E-05	1/°C	ISO 11359-2
CTE, 23°C to 80°C, xflow	9.E-05	1/°C	ISO 11359-2
Vicat Softening Temp, Rate B/120	118	°C	ISO 306
Relative Temp Index, Elec	75	°C	UL 746B
Relative Temp Index, Mech w/impact	75	°C	UL 746B
Relative Temp Index, Mech w/o impact	75	°C	UL 746B
<b>PHYSICAL</b>			

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Specific Gravity	1.28	-	ASTM D 792
Mold Shrinkage, flow, 3.2 mm	0.15 – 0.25	%	SABIC method
Mold Shrinkage, xflow, 3.2 mm	0.3 – 0.4	%	SABIC method
Density	1.28	g/cm <sup>3</sup>	ISO 1183
Water Absorption, (23°C/sat)	0.02	%	ISO 62
Moisture Absorption (23°C / 50% RH)	0.04	%	ISO 62
Melt Volume Rate, MVR at 265°C/2.16 kg	12	cm <sup>3</sup> /10 min	ISO 1133
Melt Volume Rate, MVR at 300°C/1.2 kg	26	cm <sup>3</sup> /10 min	ISO 1133
<b>FLAME CHARACTERISTICS</b>			
UL Recognized, 94HB Flame Class Rating	0.4	mm	UL 94
<b>INJECTION MOLDING</b>			
Drying Temperature	95 – 105	°C	
Drying Time	3 – 4	hrs	
Drying Time (Cumulative)	8	hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	260 – 290	°C	
Nozzle Temperature	260 – 290	°C	
Front - Zone 3 Temperature	255 – 290	°C	
Middle - Zone 2 Temperature	255 – 290	°C	
Rear - Zone 1 Temperature	250 – 280	°C	
Hopper Temperature	60 – 80	°C	
Mold Temperature	60 – 90	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	40 – 70	rpm	
Shot to Cylinder Size	30 – 80	%	
Vent Depth	0.038 – 0.076	mm	

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